

Roy Leventhal
Lynne Green

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Semiconductor Modeling

For Simulating Signal, Power,
and Electromagnetic Integrity

 Springer

SEMICONDUCTOR MODELING

SEMICONDUCTOR MODELING For Simulating Signal, Power, and Electromagnetic Integrity

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Modeling Semiconductors: For Simulating Signal, Power, and Electromagnetic Integrity

Library of Congress Control Number: 2006924288

ISBN 0-387-24159-0 e-ISBN 0-387-24160-4
ISBN 978-0387-25870-6

Printed on acid-free paper.

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Printed in the United States of America.

9 8 7 6 5 4 3 2 1

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Dedication

Dedicated to my wife Charlotte. Her skill and patience as editor helped us organize the content and express our ideas.

–Roy Leventhal

Dedicated to my husband Kelly, for endless support and patience throughout this project.

–Lynne Green

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